

Described is a photolithography "deep-well lithography" process for forming Micro-Electro-Mechanical Systems (MEMS) structures. The process differs from conventional lithography in that the surface being patterned is not the uppermost surface, but is instead the bottom of a "well" defined beneath the uppermost surface. The focal plane of the photolithography equipment is offset from the uppermost surface as appropriate to account for the depth of the well in which the pattern is to be formed. The bottom of the well is then patterned to produce a desired structure.